	Hits	Search Text	DBs
4	0	((CPP or GMR or (giant near9 magneto$4resist$6)) same transducer same (spin near12 valve)) and (seed near9 layer) and (cap$4) and (anti$4ferro$5magnet$4) and ((ferro$4magnetic or NiFe or FeMn) near16 layer) and (spacer or ((dead or Cu or copper) near9 layer)) and (pinn$4 near12 layer) and (substrate or wafer or sheet) and ((resist or photoresist or alumina) same (mask or pattern or photolithograph$4) same (undercut$4 or shadow$4) same (etch$4 or (ion near9 beam near6 etch$4) or IBE or IABE)) and ((form$4 or manufactur$4) same (pedestal or ((CPP or GMR) near6 (bottom or top) near12 (structure or stack))) same etch$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
5	0	((CPP or GMR or (giant near9 magneto$4resist$6)) same transducer same (spin near12 valve)) and (seed near9 layer) and (cap$4) and (anti$4ferro$5magnet$4) and ((ferro$4magnetic or NiFe or FeMn) near16 layer) and (spacer or ((dead or Cu or copper) near9 layer)) and (pinn$4 near12 layer) and (substrate or wafer or sheet) and ((resist or photoresist or alumina) same (mask or pattern or photolithograph$4) same (undercut$4 or shadow$4) same (etch$4 or (ion near9 beam near6 etch$4) or IBE or IABE))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
6	11	((CPP or GMR or (giant near9 magneto$4resist$6)) same transducer same (spin near12 valve)) and (seed near9 layer) and (cap$4) and (anti$4ferro$5magnet$4) and ((ferro$4magnetic or NiFe or FeMn) near16 layer) and (spacer or ((dead or Cu or copper) near9 layer)) and (pinn$4 near12 layer) and (substrate or wafer or sheet)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
7	0	((CPP or GMR or (giant near9 magneto$4resist$6)) same transducer same (spin near12 valve)) and (anti$4ferro$5magnet$4) and ((ferro$4magnetic or NiFe or FeMn) near16 layer) and (spacer or ((dead or Cu or copper) near9 layer)) and (substrate or wafer or sheet) and ((resist or photoresist or alumina) same (mask or pattern or photolithograph$4) same (undercut$4 or shadow$4) same (etch$4 or (ion near9 beam near6 etch$4) or IBE or IABE))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
8	0	((CPP or GMR or (giant near9 magneto$4resist$6)) same transducer same (spin near12 valve)) and (anti$4ferro$5magnet$4 or AFM) and ((ferro$4magnetic or NiFe or FeMn) near16 layer) and (spacer or ((dead or Cu or copper) near9 layer)) and (substrate or wafer or sheet) and ((resist or photoresist or alumina) same (mask or pattern or photolithograph$4) same (undercut$4 or shadow$4) same (etch$4 or (ion near9 beam near6 etch$4) or IBE or IABE))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
9	0	((CPP or GMR or (giant near9 magneto$4resist$6)) same transducer same (spin near12 valve)) and (anti$4ferro$5magnet$4 or AFM) and ((ferro$4magnetic or NiFe or FeMn) near16 layer) and (substrate or wafer or sheet) and ((resist or photoresist or alumina) same (mask or pattern or photolithograph$4) same (undercut$4 or shadow$4) same (etch$4 or (ion near9 beam near6 etch$4) or IBE or IABE))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
10	2	((CPP or GMR or (giant near9 magneto$4resist$6)) same transducer same (spin near12 valve)) and (substrate or wafer or sheet) and ((resist or photoresist or alumina) same (mask or pattern or photolithograph$4) same (undercut$4 or shadow$4) same (etch$4 or (ion near9 beam near6 etch$4) or IBE or IABE))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
11	8	((CPP or GMR or (giant near12 magneto$4resist$6)) same transducer) and (substrate or wafer or sheet) and ((resist or photoresist or alumina) same (mask or pattern or photolithograph$4) same (undercut$4 or shadow$4) same (etch$4 or (ion near9 beam near22 etch$4) or IBE or IABE))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
12	37	((CPP or GMR or (giant near12 magneto$4resist$6) or (magnetic near9 head)) same transducer) and (substrate or wafer or sheet) and ((resist or photoresist or alumina) same (mask or pattern or photolithograph$4) same (undercut$4 or shadow$4) same (etch$4 or (ion near9 beam near22 etch$4) or IBE or IABE))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
13	42	((CPP or GMR or (giant near12 magneto$4resist$6) or (magnetic near9 head)) same transducer) and (substrate or wafer or sheet) and ((resist or photoresist or alumina) same (mask or pattern or photolithograph$4) same (undercut$4 or shadow$4) same ((ion$4 near16 mill$4) or etch$4 or (ion near9 beam near22 etch$4) or IBE or IABE))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
14	0	((CPP or GMR or (giant near12 magneto$4resist$6) or (magnetic near9 head)) same transduc) and (substrate or wafer or sheet) and ((resist or photoresist or alumina) same (mask or pattern or photolithograph$4) same (undercut$4 or shadow$4) same ((ion$4 near16 mill$4) or etch$4 or (ion near9 beam near22 etch$4) or IBE or IABE))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
15	108	((CPP or GMR or (giant near12 magneto$4resist$6) or (magnetic near9 head)) same transduc$4) and (substrate or wafer or sheet) and ((resist or photoresist or alumina) same (mask or pattern or photolithograph$4) same (undercut$4 or shadow$4) same ((ion$4 near16 mill$4) or etch$4 or (ion near9 beam near22 etch$4) or IBE or IABE))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
16	8	((CPP or GMR or (giant near12 magneto$4resist$6) or (magnetic near9 head)) same transduc$4) and (substrate or wafer or sheet) and ((resist or photoresist or alumina) same (mask or pattern or photolithograph$4) same (undercut$4 or shadow$4) same ((ion$4 near16 mill$4) or etch$4 or (ion near9 beam near22 etch$4) or IBE or IABE)) and overhang	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
17	64	((CPP or GMR or (giant near12 magneto$4resist$6) or (magnetic near9 head)) same transduc$4) and (substrate or wafer or sheet) and ((resist or photoresist or alumina) same (mask or pattern or photolithograph$4) same (undercut$4 or shadow$4) same ((ion$4 near16 mill$4) or etch$4 or (ion near9 beam near22 etch$4) or IBE or IABE)) and (overhang or overetch$4 or ((rotat$4 or mov$3 or tilt$4) same (substrate or wafer or GMR or (ion near9 source))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
18	0	((CPP or GMR or (giant near12 magneto$4resist$6) or (magnetic near9 head)) same transduc$4) and (substrate or wafer or sheet) and ((resist or photoresist or alumina) same (mask or pattern or photolithograph$4) same (undercut$4 or shadow$4)) and (((ion$4 near16 mill$4) or etch$4 or (ion near9 beam near22 etch$4) or IBE or IABE) same (rotat$4 or spin$4) same (tilt$4 or slop$4 or undercut$4 or overhang) same angle same (vary4 or different or adjust)) and (overhang or overetch$4 or ((rotat$4 or mov$3 or tilt$4) same (substrate or wafer or GMR or (ion near9 source))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
19	3	((CPP or GMR or (giant near12 magneto$4resist$6) or (magnetic near9 head)) same transduc$4) and (substrate or wafer or sheet) and ((resist or photoresist or alumina) same (mask or pattern or photolithograph$4)) and (((ion$4 near16 mill$4) or etch$4 or (ion near9 beam near22 etch$4) or IBE or IABE) same (rotat$4 or spin$4) same (tilt$4 or slop$4 or undercut$4 or overhang) same angle same (vary4 or different or adjust)) and (overhang or overetch$4 or ((rotat$4 or mov$3 or tilt$4) same (substrate or wafer or GMR or (ion near9 source)))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
20	3	((CPP or GMR or (giant near12 magneto$4resist$6) or (magnetic near9 head)) same transduc$4) and (substrate or wafer or sheet) and (mask or pattern or photolithograph$4) and (((ion$4 near16 mill$4) or etch$4 or (ion near9 beam near22 etch$4) or IBE or IABE) same (rotat$4 or spin$4) same (tilt$4 or slop$4 or undercut$4 or overhang) same angle same (vary4 or different or adjust)) and (overhang or overetch$4 or ((rotat$4 or mov$3 or tilt$4) same (substrate or wafer or GMR or (ion near9 source)))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
21	12	(CPP or GMR or (giant near12 magneto$4resist$6) or (magnetic near9 head) or stack) and (substrate or wafer or sheet) and (mask or pattern or photolithograph$4) and (((ion$4 near16 mill$4) or etch$4 or (ion near9 beam near22 etch$4) or IBE or IABE) same (rotat$4 or spin$4) same (tilt$4 or slop$4 or undercut$4 or overhang) same angle same (vary4 or different or adjust)) and (overhang or overetch$4 or ((rotat$4 or mov$3 or tilt$4) same (substrate or wafer or GMR or (ion near9 source)))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
22	0	(CPP or GMR or (giant near12 magneto$4resist$6) or (magnetic near9 head) or stack) and (substrate or wafer or sheet) and (mask or pattern or photolithograph$4) and (((ion$4 near16 mill$4) or etch$4 or (ion near9 beam near22 etch$4) or IBE or IABE) same (rotat$4 or spin$4) same (tilt$4 or slop$4 or undercut$4 or overhang) same angle same (vary4 or different or adjust)) and ((ion near9 beam) same (inciden$3 or bombard$4 or imping$4) same (debth or collimat$4 or broad) same angle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
23	6	(("20050058952") or ("20050106509") or ("6759084") or ("7016168") or ("6905811") or ("6770382")).PN.	US-PGPUB; USPAT

	Hits	Search Text	DBs
24	0	(CPP or GMR or (giant near12 magneto$4resist$6) or (magnetic near9 head) or stack or pedestal) and (substrate or wafer or sheet) and (mask or pattern or photolithograph$4 or ((resist or photoresist) near12 (mask or structure or pattern))) and (((ion$4 near16 mill$4) or etch$4 or (ion near9 beam near22 etch$4) or IBE or IABE) same (rotat$4 or spin$4) same (tilt$4 or slop$4 or (vary$4 near6 angle) or (chang$4 near8 angle) or (different near9 angle))) and (((ion near6 beam near9 source) or (ion near9 source) or (ion near9 (gun or module))) same angle same (vary4 or different or adjust or chang$4)) and ((rotat$4 or mov$3 or tilt$4) same (substrate or wafer)) and (shadow$5 or undercut$4 or overhang)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
25	4	(substrate or wafer or sheet) and (mask or pattern or photolithograph$4 or ((resist or photoresist) near12 (mask or structure or pattern))) and (((ion$4 near16 mill$4) or etch$4 or (ion near9 beam near22 etch$4) or IBE or IABE) same (rotat$4 or spin$4) same (tilt$4 or slop$4 or (vary$4 near6 angle) or (chang$4 near8 angle) or (different near9 angle))) and (((ion near6 beam near9 source) or (ion near9 source) or (ion near9 (gun or module))) same angle same (vary4 or different or adjust or chang$4)) and ((rotat$4 or mov$3 or tilt$4) same (substrate or wafer)) and (shadow$5 or undercut$4 or overhang)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
26	1	("5420880").PN.	US-PGPUB; USPAT

	Hits	Search Text	DBs
27	24	(substrate or wafer or sheet) and (mask or pattern or photolithograph$4 or ((resist or photoresist) near12 (mask or structure or pattern))) and (((ion$4 near16 mill$4) or etch$4 or (ion near9 beam near22 etch$4) or IBE or IABE) same (tilt$4 or slop$4 or rotat$4 or spin$4 or (vary$4 near6 angle) or (chang$4 near8 angle) or (different near9 angle))) and (((ion near6 beam near9 source) or (ion near9 source) or (ion near9 (gun or module))) same angle same (vary4 or different or adjust or chang$4 or var$4 or rang$4)) and ((rotat$4 or mov$3 or tilt$4 or spin$4) same (substrate or wafer)) and (shadow$5 or undercut$4 or overhang)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
28	0	(mask or pattern or photolithograph$4 or ((resist or photoresist) near12 (mask or structure or pattern))) and (((ion near9 mill$4) or (ion near9 beam) or IBE or (ion near6 beam near9 source) or (ion near9 source) or (ion near9 (gun or module))) same (angle or tilt$4 or rotat$4 or spin$4 or slop$4) same (vary4 or different or adjust or chang$4 or var$4 or rang$4)) and ((rotat$4 or mov$3 or tilt$4 or spin$4) same (substrate or wafer)) and (shadow$5 or undercut$4 or overhang) and (((sidewall or side) near22 profile) same hyperbol$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
29	51	(mask or pattern or photolithograph$4 or ((resist or photoresist) near12 (mask or structure or pattern))) and (((ion near9 mill$4) or (ion near9 beam) or IBE or (ion near6 beam near9 source) or (ion near9 source) or (ion near9 (gun or module))) same (angle or tilt$4 or rotat$4 or spin$4 or slop$4) same (vary4 or different or adjust or chang$4 or var$4 or rang$4)) and ((rotat$4 or mov$3 or tilt$4 or spin$4) same (substrate or wafer)) and (shadow$5 or undercut$4 or overhang) and (((sidewall or side) near22 profile) or hyperbol$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
30	48	S29 NOT S27	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB